

PEPE ROHE SITE COMPONENTS

One Package Regulator Series

0.65A Output, Fully Integrated, **Step-down Switching Power Supply Module**

BZ6Axx06GM Series

General Description

The BZ6Axx06GM is a fully integrated power supply module that is useful for shortening the product at the design period and shortening the product launch time for electronics product, communication of portable it, and various applications industrial etc.

BZ6Axx06GM is based on a high efficiency 6MHz synchronous step-down switching regulator. It provides up to 0.65A load current and an input voltage range from 2.3V to 5.5V, optimized for battery powered portable applications.

BZ6Axx06GM has a mode control pin that allows the user to select Forced PWM(Pulse Width Modulation) mode or PFM(Pulse Frequency Modulation) and PWM auto change mode utilized power save operation at light load current.

Features

- No External components required SMPS
- Fast transient response
- Automatic PFM/PWM operation
- Forced PWM operation
- Internal Soft Start
- Under voltage lockout
- Over current protection
- Thermal shutdown
- Ultra small and low profile package

●Lineup

Part No.	Output voltage		
BZ6A1206GM	1.20V		
BZ6A7D06GM	1.25V		

Pin Configuration(s) (Top View)

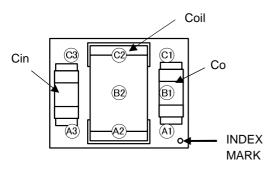


Figure 2. Pin Configuration(s)

Applications

Smart Phones, Cell phones, Portable applications, POL applications, RF applications, and USB Line Application

Package(s)

BGA-MD

W(Typ.) x D(Typ.) x H(Max.) 2.90mm x 2.30mm x 1.00mm



BGA-MD

Typical Application Circuit(s)

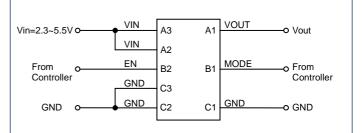


Figure 1. Typical Application Circuit(s)

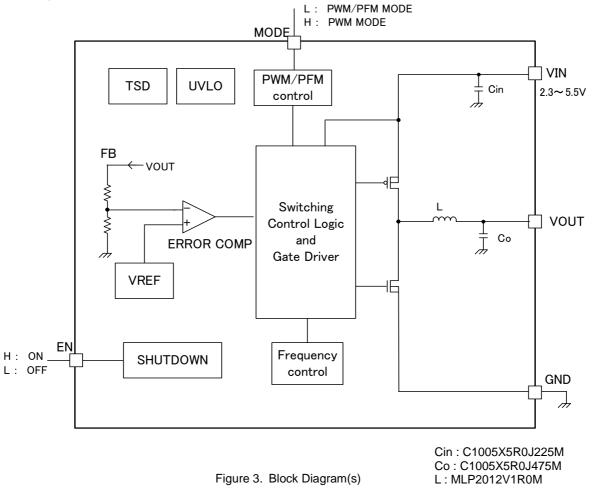
Pin Description(s)

Pin No.	Symbol	Name	Function
1	A1	VOUT	Output pin
2	A2	VIN	Power supply input pin
3	A3	VIN	Power supply input pin
4	B1	MODE	Forced PWM mode pin
5	B2	EN	Enable pin
6	C1	GND	GND pin
7	C2	GND	GND pin
8	C3	GND	GND pin

〇製品構造:シリコンモノリシック集積回路 〇耐放射線設計はしておりません

BZ6Axx06GM Series

Block Diagram(s)



Description of Block(s)

The BZ6Axx06GM are a synchronous step-down DC/DC converter that achieves fast transient response from light load to heavy load by hysteretic PWM control system and current constant PFM control system.

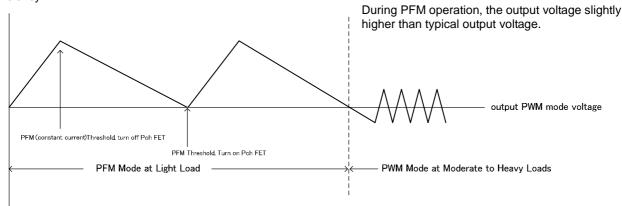
OPWM control

BZ6Axx06GM operates by hysteretic PWM control. This scheme ensures fast switching, high efficiency, and fast transient response.

When the output voltage is below the VREF voltage, the error comparator output is low to high and turning on P-channel MOSFET until above the VREF voltage and minimum on time.

OPFM control

At light load the regulator and MODE=low, the regulator operates with reduced switching frequency and improves the efficiency.





Description of operations

1) Shutdown

If the EN input pin set to low (<0.4V), all circuit are shut down and the regulator is standby mode. Do not leave the EN pin floating.

2) Soft start function

The regulator has a soft start circuit that reduces in-rush current at start-up. Typical start up times with a 4.7uF output capacitor is 120usec.

3) Current limit

The BZ6Axx06GM has a current limit circuit that protects itself and external components during overload condition.

4) Under Voltage Lock Out (UVLO) The BZ6Axx06GM has a Under Voltage Lock Out circuit that turn off device when VIN>2.05V(typ.)

5) FORCED PWM MODE

Setting MODE pin high (>1.4V) places the regulator in forced PWM. This control provides noise reduction and output stability.

Do not leave the MODE pin floating.

6) TSD

The BZ6Axx06GM has a thermal shutdown feature to protect the device if the junction temperature exceeds 150°C.In thermal shutdown, the DRIVER is disabled.

This circuit is only to cut off the IC from thermal runaway, and has not been design to protect or guarantee the IC. Therefore, the user should not plan to activate this circuit with continued operation in mind.

●Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Maximum input power supply voltage	VIN	7	V
Power dissipation	Pd	0.75 *1	W
Operating temperature range	Topr	-40 to +85	C°
Storage temperature range	Tstg	-55 to +125	C°
Junction temperature	Tjmax	+125	°C

*1 When mounted on the specified PCB (55mm x 63mm), Deducted by 3.9m W/c when used over Ta=25c

Recommended Operating Rating(s)

Deremeter	Symbol	Rating			Unit
Parameter		Min.	Тур.	Max.	Unit
Input voltage	VIN	2.3		5.5	V
Output current	IOUT	0		0.65	А

● Electrical Characteristic(s) (unless otherwise specified VIN=3.6V, Ta=25°C)

Item		Symbol	Rating		Unit	Condition	
		Symbol	Min.	Тур.	Max.	Unit	Condition
Switching reg	ulator】						
Output voltage a	ocuracy	VOUTA	-2.5	-	+2.5	%	MODE:H(PWM Operation)
	leculacy	VOUL	-2.5	-	+3.5	70	MODE:L(PFM Operation)
[Soft start]		-					
Soft start time		Tss	65	120	240	usec	
[Control]							
EN pin control	Operation	VENH	1.4	-	VIN	V	
voltage	Non Operation	VENL	0	-	0.4	V	
MODE pin	Operation	VMODEH	1.4	-	VIN	V	Forced PWM
control voltage	Non Operation	VMODEL	0	-	0.4	V	Automatic PFM/PWM
[UVLO]				ľ			
Protect threshold	d voltage	Uvth	1.95	2.05	2.15	V	
Hysteresis		Uvhy	50	100	150	mV	
Circuit current]						
Operating quiescent current		IINS	-	45	72	uA	EN:H, MODE:L, VOUT=3.6V forced Not switching
Shutdown currer	nt	SHD	-	0	1	uA	EN=0V

• Electrical characteristic curves (Reference data) BZ6A1206GM(1.20V OUTPUT)

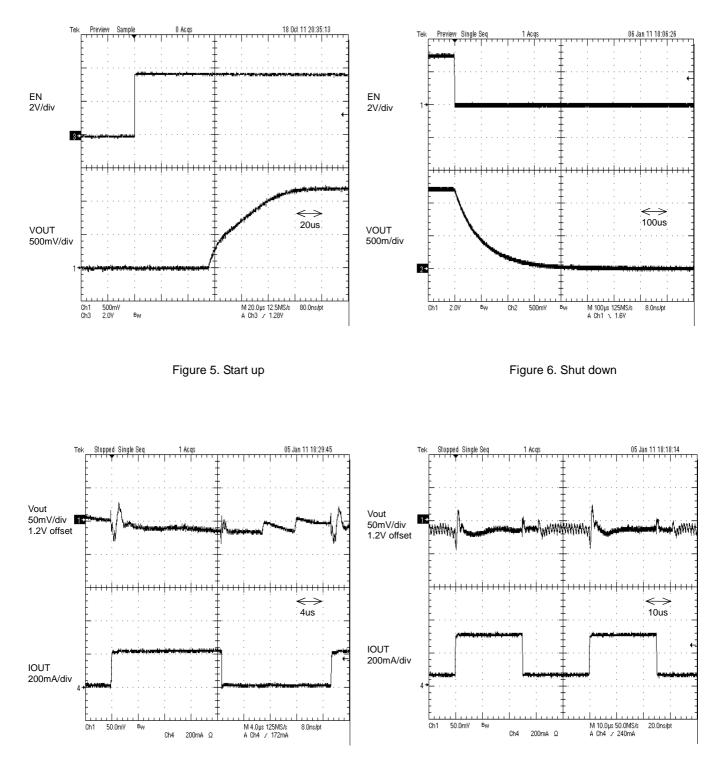


Figure 7. Load transient response 5mA to 200mA tr=tf=100ns, MODE : Low

Figure 8. Load transient response 50mA to 350mA tr=tf=100ns, MODE : Low

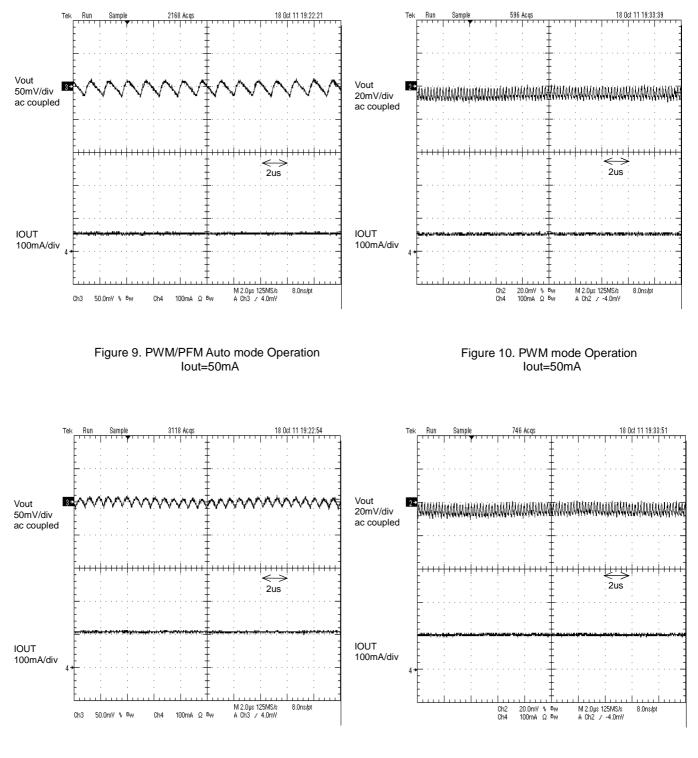
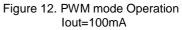


Figure 11. PWM/PFM Auto mode Operation Iout=100mA



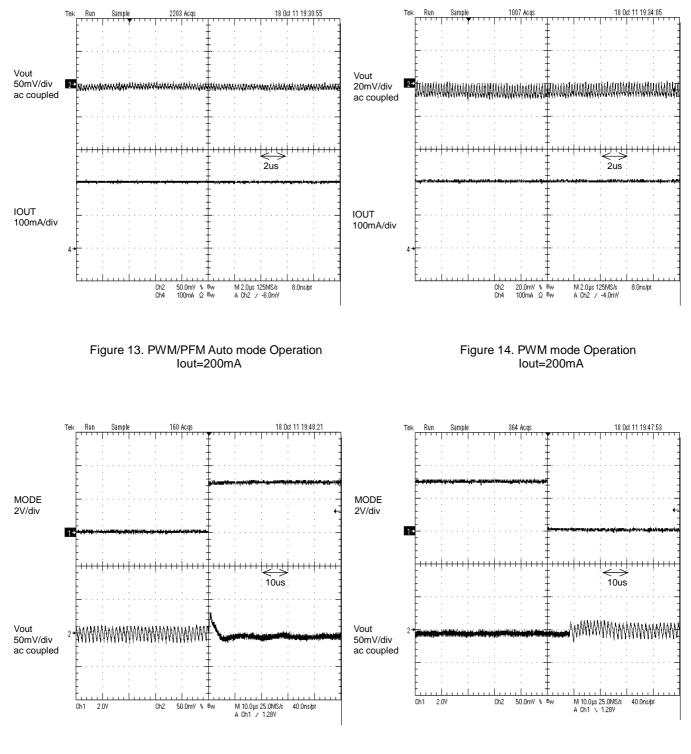
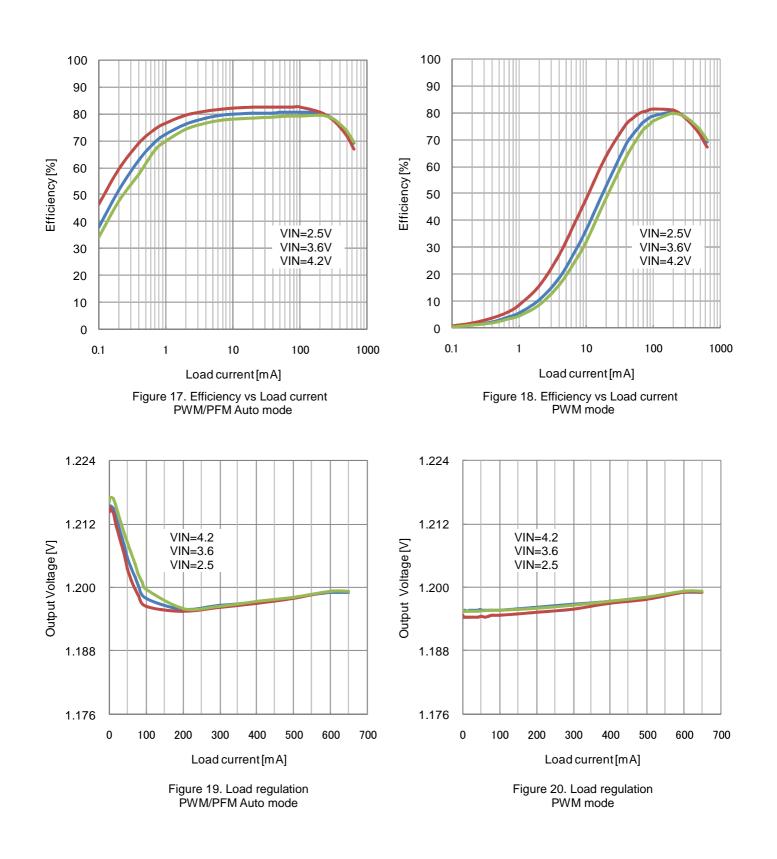


Figure 15. Mode Change Response MODE : Low to High

Figure 16. Mode Change Response MODE : High to Low



• Electrical characteristic curves (Reference data) BZ6A7D06GM(1.25V OUTPUT)

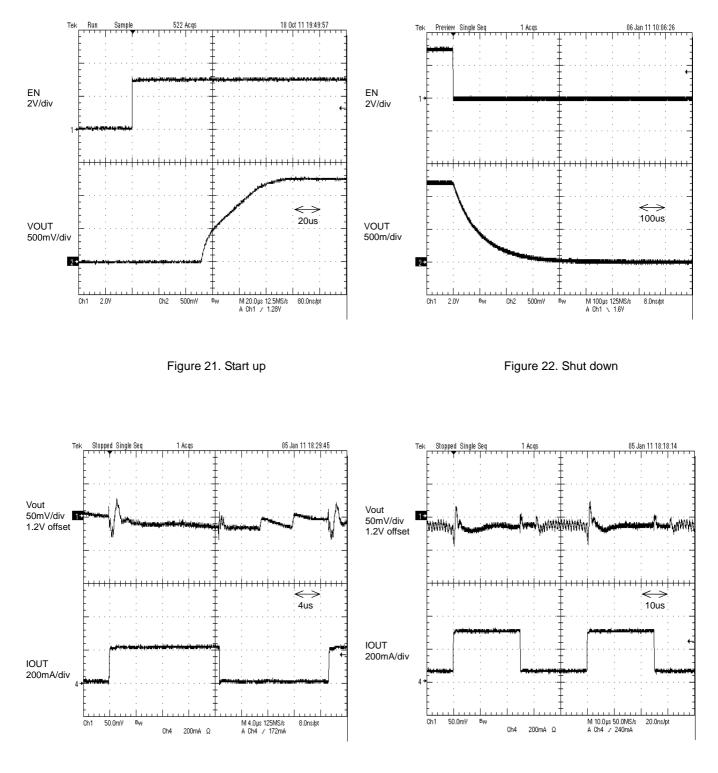


Figure 23. Load transient response 5mA to 200mA tr=tf=100ns, MODE : Low

Figure 24. Load transient response 50mA to 350mA tr=tf=100ns, MODE : Low

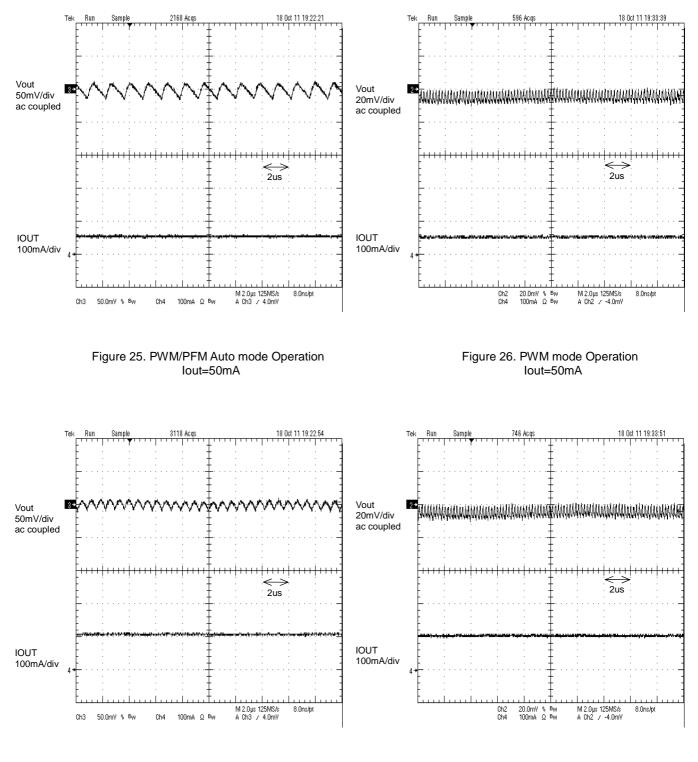


Figure 27. PWM/PFM Auto mode Operation lout=100mA

Figure 28. PWM mode Operation Iout=100mA

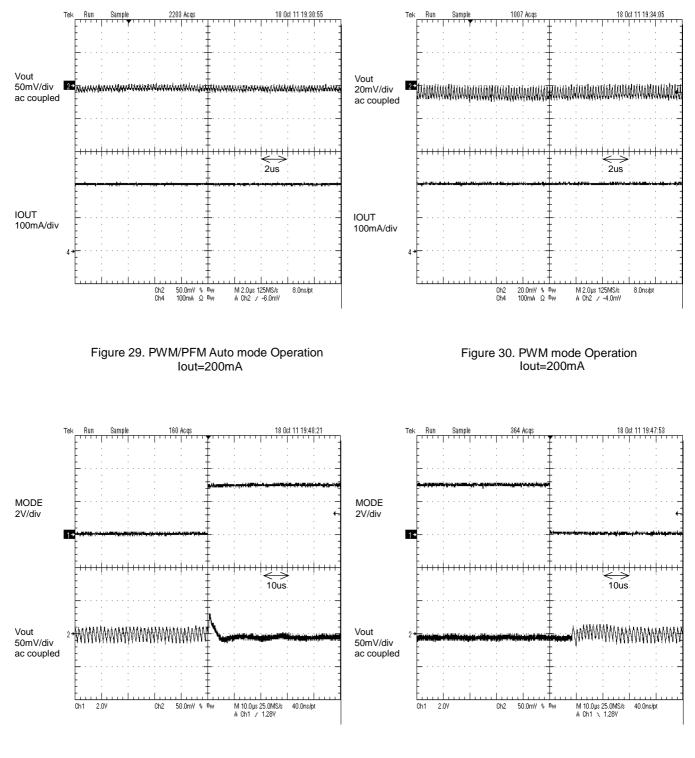
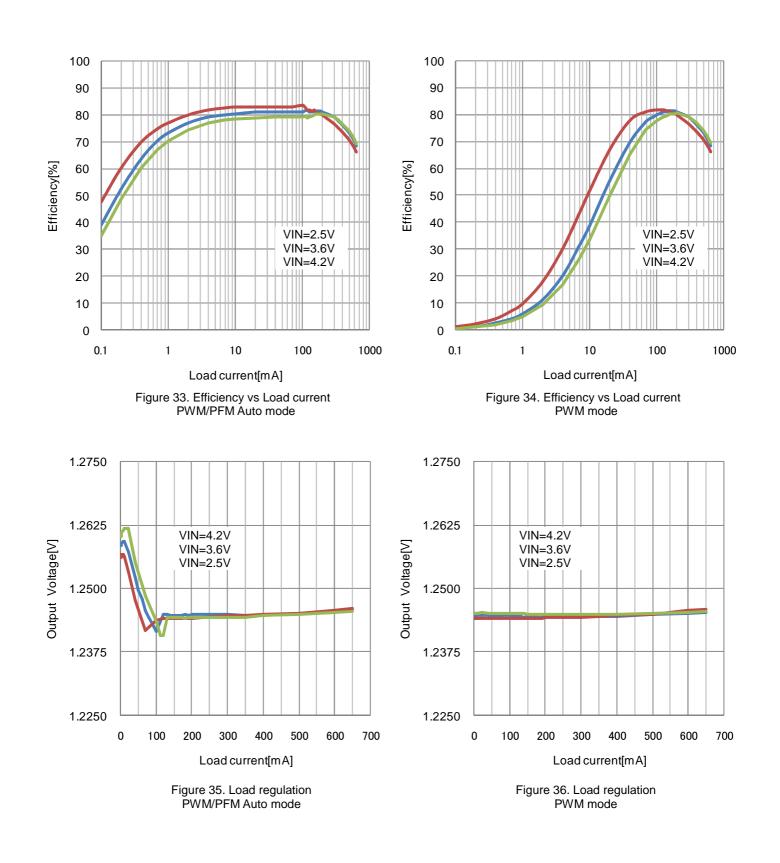


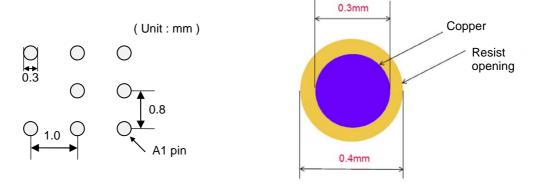
Figure 31. Mode Change Response MODE : Low to High

Figure 32. Mode Change Response MODE : High to Low

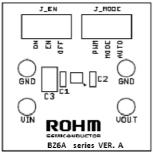


●PC Board layout

The suggested PCB layout for the BZ6Axx06GM is shown in Figure.







BZ6A series VER. A

Figure 38. PCB layout (Mount side)

Figure 39. PCB layout (solder side)

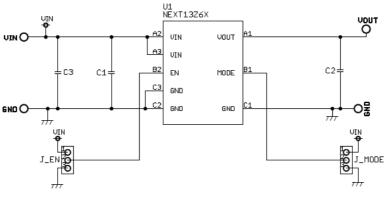


Figure 40. PCB Circuit

Caution of use

1) Absolute maximum ratings

An excess in the absolute maximum rating, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2) GND voltage

The potential of GND pin must be minimum potential in all condition. As an exception, the circuit design allows voltages up to -0.3 V to be applied to the IC pin.

3) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

4) Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

5) Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

6) Mutual impedance

Power supply and ground wiring should reflect consideration of the need to lower mutual impedance and minimize ripple as much as possible (by making wiring as short and thick as possible or rejecting ripple by incorporating inductance and capacitance).

7) Thermal shutdown Circuit (TSD Circuit)

This model IC has a built-in TSD circuit. This circuit is only to cut off the IC from thermal runaway, and has not been design to protect or guarantee the IC. Therefore, the user should not plan to activate this circuit with continued operation in mind.

8) Regarding input pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of these P layers with the N layers of other elements, creating a parasitic diode or transistor. For example, as shown in the figures below, the relation between each potential is as follows:

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.

When GND > Pin B, the P-N junction operates as a parasitic transistor.

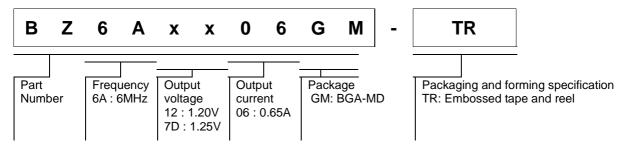
Parasitic diodes can occur inevitable in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin, should not be used.

Status of this document

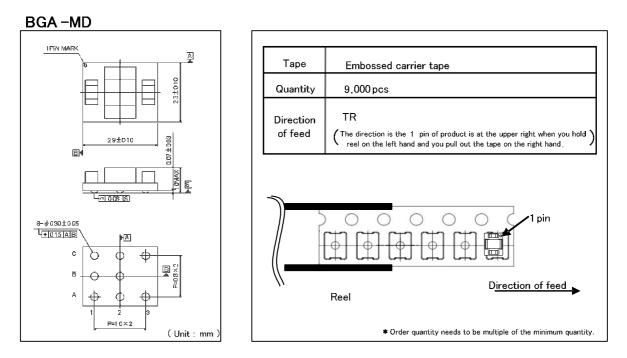
The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document formal version takes priority

Ordering Information



Physical Dimension Tape and Reel Information



●改訂履歴

Date	Revision	Changes				
24.Jul.2012	001	New Release				

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